



1765  
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re U.S. Patent Application

) Confirmation No.: 2326

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) I hereby certify that this  
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Patents / PO Box 1450 / Alexandria,  
Virginia 22313-1450, on November  
25, 2003.

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Gerald T. Shekleton

) Gerald T. Shekleton Reg. No. 27,466

Serial No.: 10/049,875

Filed: February 12, 2002

For: **SILICON WAFER AND METHOD  
FOR MANUFACTURE THEREOF,  
AND METHOD OF EVALUATION  
OF SILICON WAFER**

Art Unit: 1765

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

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Sir:

Pursuant to 37 C.F.R. §1.97, a list of documents is disclosed on the attached Form PTO-1449 that may be material to the examination of this application. The listed Documents are enclosed herewith.

Each item of information contained in the information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement.

No inferences should be drawn that the attached list represents a comprehensive investigation, or that any material disclosed is equivalent to the subject invention. In addition, none of the documents that have publication dates prior to the priority date of the above application anticipate the invention in this application.

The cited document(s) disclose numerous specific features. There has been no attempt to list each and every feature disclosed by each document. The Examiner is requested to review the document(s) and determine the extent of the materiality of the document disclosures with respect to the present invention.

The discussion of any art and the citation of any document(s) herein is not to be construed as an admission that the art or document disclosure is necessarily within the invention field of endeavor, that the art or document disclosure is necessarily prior in time to a particular date which may be relevant to the instant patent application, and/or that the art or document disclosure is otherwise necessarily prior art as defined by the patent law with respect to the instant invention and application.

Also, there is reserved the right to later set forth how the instant invention is distinguished over the disclosure of any document or other art, including the disclosures of the art and document(s) recited herein, that may be cited by the Examiner in rejecting a claim in the instant patent application. The recitation herein of the art and document(s) is not to be construed as an assertion that more pertinent art could not possibly be in existence.

Respectfully submitted,  
**WELSH & KATZ, LTD.**

By *Gerald T. Shekleton*  
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Dated: November 25, 2003

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Sheet 1 of 1

(Rev. 5/92) Comparable to Form PTO-1449		U.S. Department of Commerce Patent and Trademark Office		Atty. Docket No. 86397	Serial No. 10/049,875
INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)		Applicant Satoshi Komiya et al.			
		Filing Date February 12, 2002		Group 1765	

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U.S. PATENT DOCUMENTS							
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
		6,077,343	06/20/2000	Iida et al.	117	2	
		6,261,361	07/17/2001	Iida et al.	117	19	

FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Name of Patentee	Class	Subclass	Translation Yes      No

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							

Examiner				Date Considered			
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\*Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.